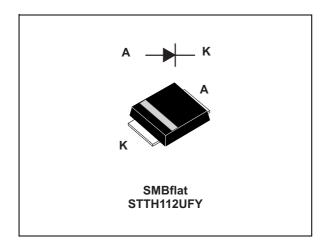


Automotive high voltage ultrafast rectifier

Datasheet - production data



Features

- Very low conduction losses
- · Negligible switching losses
- Low forward and reverse recovery times
- · High junction temperature
- AEC-Q101 qualified
- ECOPACK®2 compliant component

Description

The STTH112-Y, which is using ST's new 1200 V planar technology, is especially suited for switching mode base drive and transistor circuits.

The device is also intended for use as a free wheeling diode in power supplies and other power switching applications in automotive functions.

Table 1. Device summary

Symbol	Value
I _{F(AV)}	1 A
V_{RRM}	1200 V
T _{j (max)}	175 °C
V _{F (typ)}	1.1 V
T _{rr (typ)}	53 ns

Characteristics STTH112-Y

1 Characteristics

Table 2. Absolute ratings (limiting values at T_i = 25 °C, unless otherwise specified)

Symbol	Parameter			Value	Unit
V_{RRM}	Repetitive peak reverse voltage	Repetitive peak reverse voltage			
I _{F(AV)}	Average forward current	35 °C, δ = 0.5	1	Α	
I _{FSM}	Forward Surge current $t_p = 8.3 \text{ ms}$			18	Α
T _{stg}	Storage temperature range	-65 to + 175	°C		
T _j ⁽¹⁾	Operating temperature range	-40 to + 175	°C		

^{1.} $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
R _{th(j-l)}	Junction to lead	20	°C/W

Table 4. Static electrical characteristics

Symbol	Parameter	Tests conditions		Min.	Тур.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage current	T _j = 25 °C	V _R = V _{RRM}			5	μA
'R'	Reverse leakage current	T _j = 125 °C			1	50	μΛ
V _E (2)	Forward voltage drop	T _j = 25 °C	Ι – 1 Λ			1.9	V
V F` ′	V _F ⁽²⁾ Forward voltage drop		I _F = 1 A		1.10	1.55	V

^{1.} Pulse test: $tp = 5 \text{ ms}, \delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 1.25 \text{ x } I_{F(AV)} + 0.30 I_{F^{2}(RMS)}$$

Table 5. Dynamic electrical characteristics

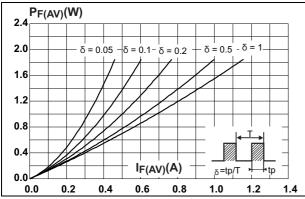
Symbol	Parameter	Tests conditions		Min.	Тур.	Max.	Unit
t _{rr}	Reverse recovery time	T _j = 25 °C	I _F = 0.5 A, I _{rr} = 0.25 A I _R = 1 A		53	75	ns
t _{fr}	Forward recovery time		L = 1 Δ dL/dt = 50 Δ/μs			500	
V _{FP}	Forward recovery voltage	$T_j = 25 ^{\circ}\text{C}$ $V_{FR} = 4.5 ^{\circ}\text{V}$	$V_{FR} = 4.5 \text{ V}$		20	30	٧

^{2.} Pulse test: $tp = 380 \mu s$, $\delta < 2\%$

STTH112-Y Characteristics

Figure 1. Average forward power dissipation versus average forward current

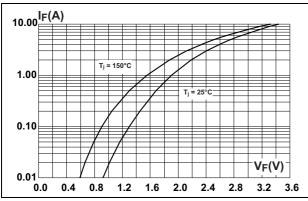
Figure 2. Forward voltage drop versus forward current (typical values)



1.00 1.00 1.00 0.10 0.01 0.0 0.4 0.8 1.2 1.6 2.0 2.4 2.8

Figure 3. Forward voltage drop versus forward current (maximum values)

Figure 4. Relative variation of thermal impedance junction to lead versus pulse duration



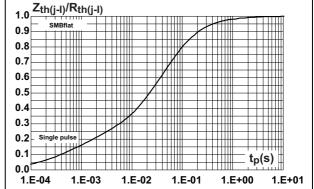
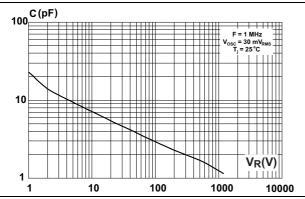
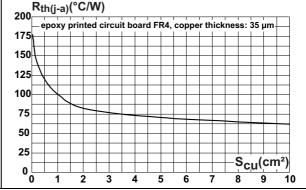


Figure 5. Junction capacitance versus reverse voltage applied (typical values)

Figure 6. Thermal resistance junction to ambient versus copper surface under each lead





Package information STTH112-Y

Package information 2

- Epoxy meets UL94,V0
- Lead-free package
- Band indicates cathode

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

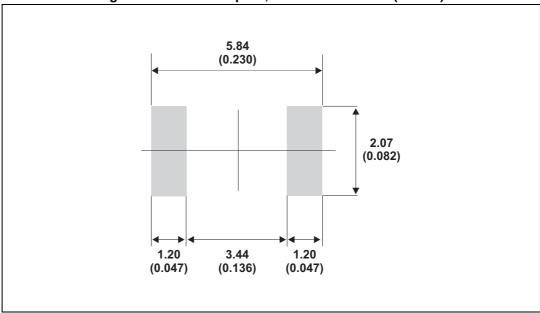
D L2 2x Е E1 L1 2x b

Figure 7. SMBflat dimensions definitions

Table 6. SMBflat dimension values

	Dimensions					
Ref.		Millimeters		Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	0.90		1.10	0.035		0.043
b	1.95		2.20	0.077		0.087
С	0.15		0.40	0.006		0.016
D	3.30		3.95	1.30		0.156
E	5.10		5.60	0.200		0.220
E1	4.05		4.60	0.189		0.181
L	0.75		1.50	0.029		0.059
L1		0.40			0.016	
L2		0.60			0.024	

Figure 8. SMBflat footprint, dimensions in mm (inches)



Ordering information STTH112-Y

3 Ordering information

Table 7. Ordering information

Order codes	Marking	Package	Weight	Base qty	Delivery mode
STTH112UFY	F112Y	SMBflat	50 mg	5000	Tape and reel

4 Revision history

Table 8. Document revision history

Date	Revision	Changes
04-Feb-2014	1	Initial release.

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